

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
)
Takayama et al.)
)
Serial No.: 10/672,521)
)
Filed: September 26, 2003)
)
For: Wiring Material, Semiconductor Device)
Provided With A Wiring Using The Wiring)
Material And Method of Manufacturing)
Thereof)
)
Examiner: Cheung Lee)
)
Art Unit: 2812)

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT F (AFTER FINAL)

In response to the Final Rejection of July 20, 2006, a RCE being filed herewith, please amend the above-identified application as follows: